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(12) **United States Design Patent**
Fukumoto et al.

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(54) **SEMICONDUCTOR DEVICE**

- (75) Inventors: **Takakazu Fukumoto**, Tokyo (JP);
Muneharu Tokunaga, Tokyo (JP);
Tetsuya Matsuura, Tokyo (JP)
- (73) Assignee: **Mitsubishi Denki Kabushiki Kaisha**,
Tokyo (JP)
- (**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

- Aug. 31, 2001 (JP) 2001-025619
- (51) **LOC (7) Cl.** **13-03**
- (52) **U.S. Cl.** **D13/182**
- (58) **Field of Search** D13/182; D14/114;
174/52.1, 52.2, 52.4-52.5, 16.3; 206/710,
719; 257/254, 657, 697, 730, 738; 324/755,
765; 361/752, 798, 820, 718, 730

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Primary Examiner—Ted Shooman
Assistant Examiner—Selina Sikder
 (74) *Attorney, Agent, or Firm*—Oblon, Spivak, McClelland,
 Maier & Neustadt, P.C.

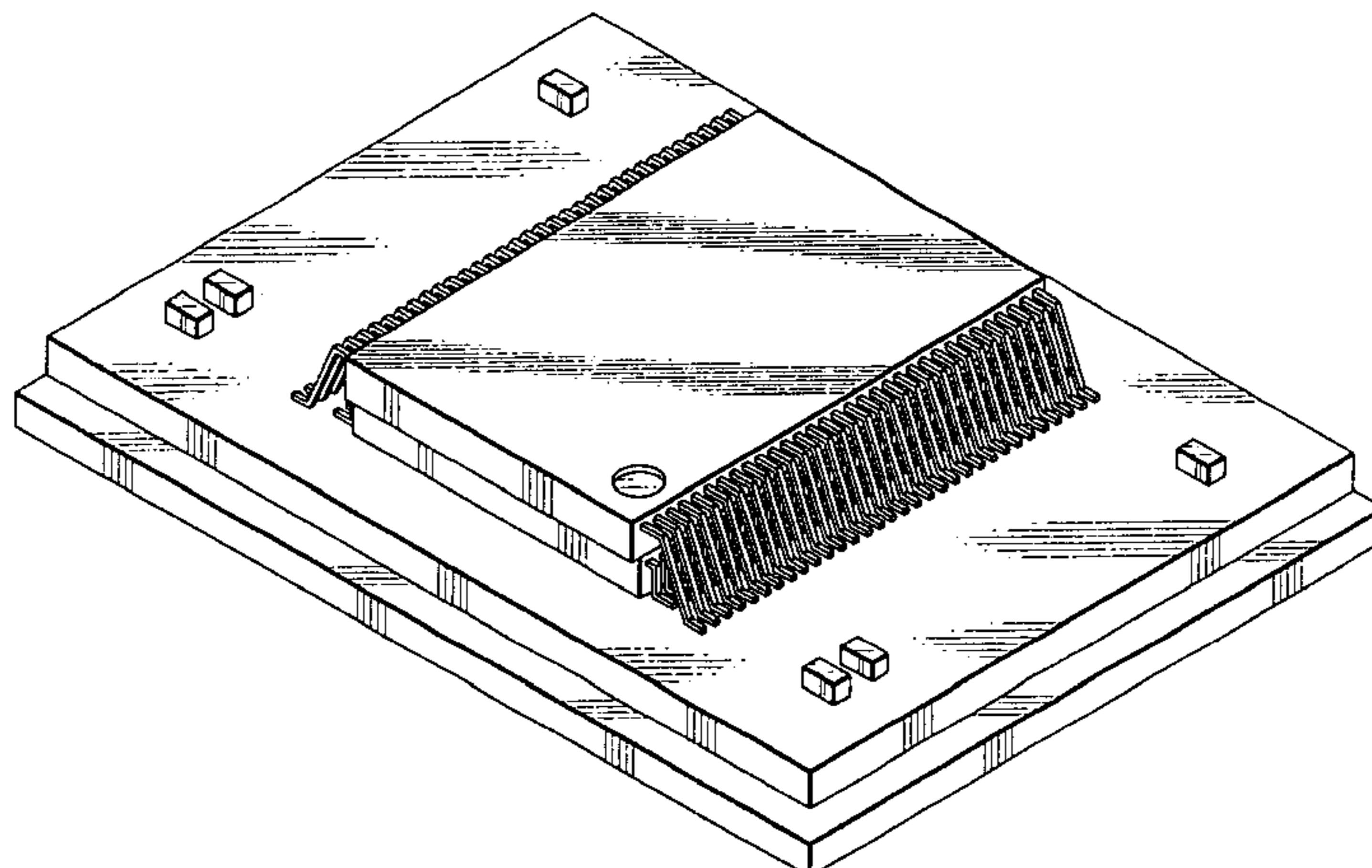
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a semiconductor device, showing our new design;
 FIG. 2 is a front, bottom and right side perspective view thereof;
 FIG. 3 is a front elevational view thereof, the rear elevational view is omitted as that is the same image to the front elevational view thereof;
 FIG. 4 is a right side elevational view thereof, the left side elevational view is omitted as that is symmetrical to the right side elevational view thereof;
 FIG. 5 is a top plan view thereof;
 FIG. 6 is a bottom plan view thereof; and,
 FIG. 7 is a cross-sectional view thereof, taken along line 7—7 of FIG. 4, with the internal system omitted.

1 Claim, 4 Drawing Sheets



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FIG. 1

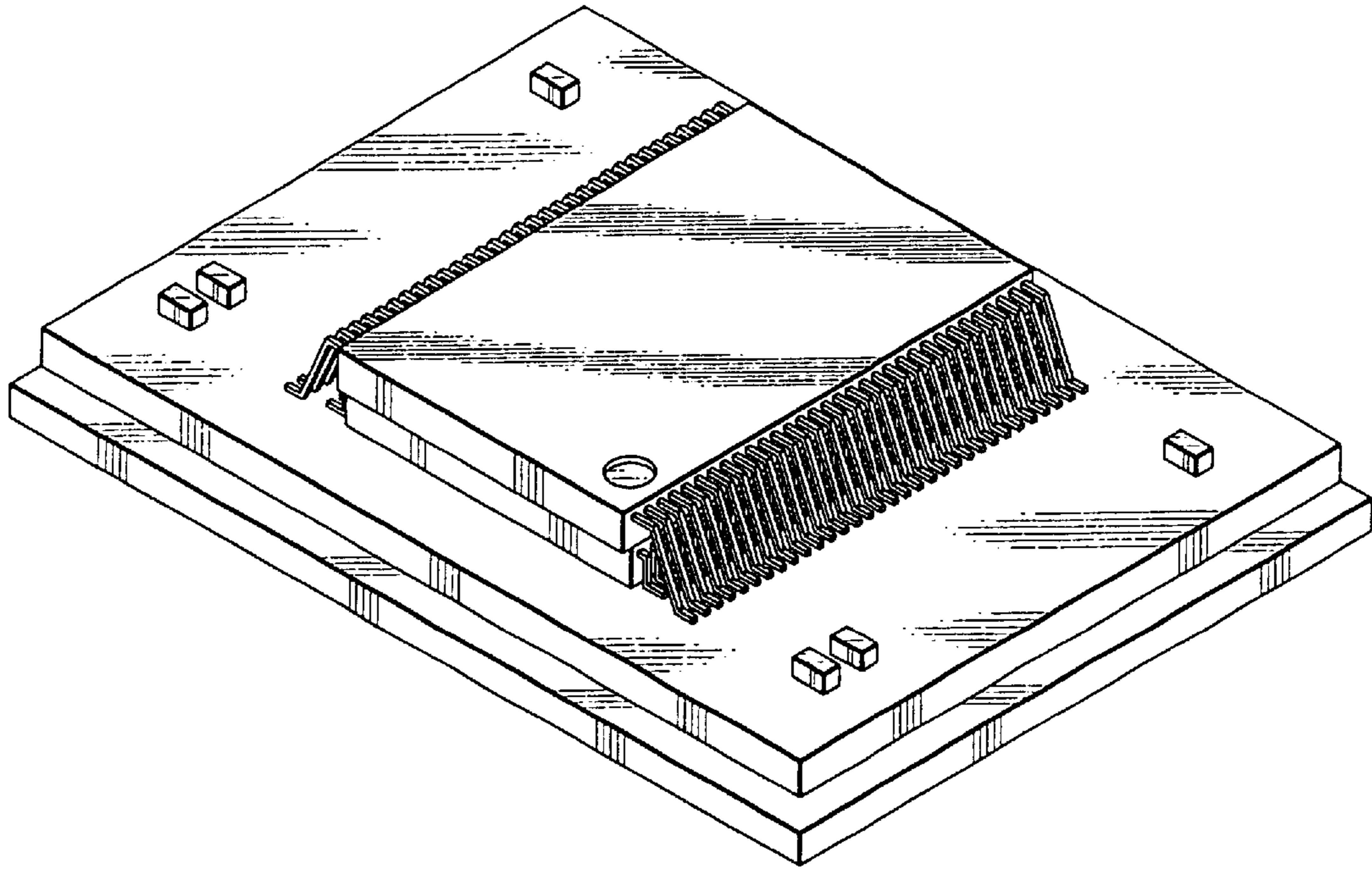


FIG. 2

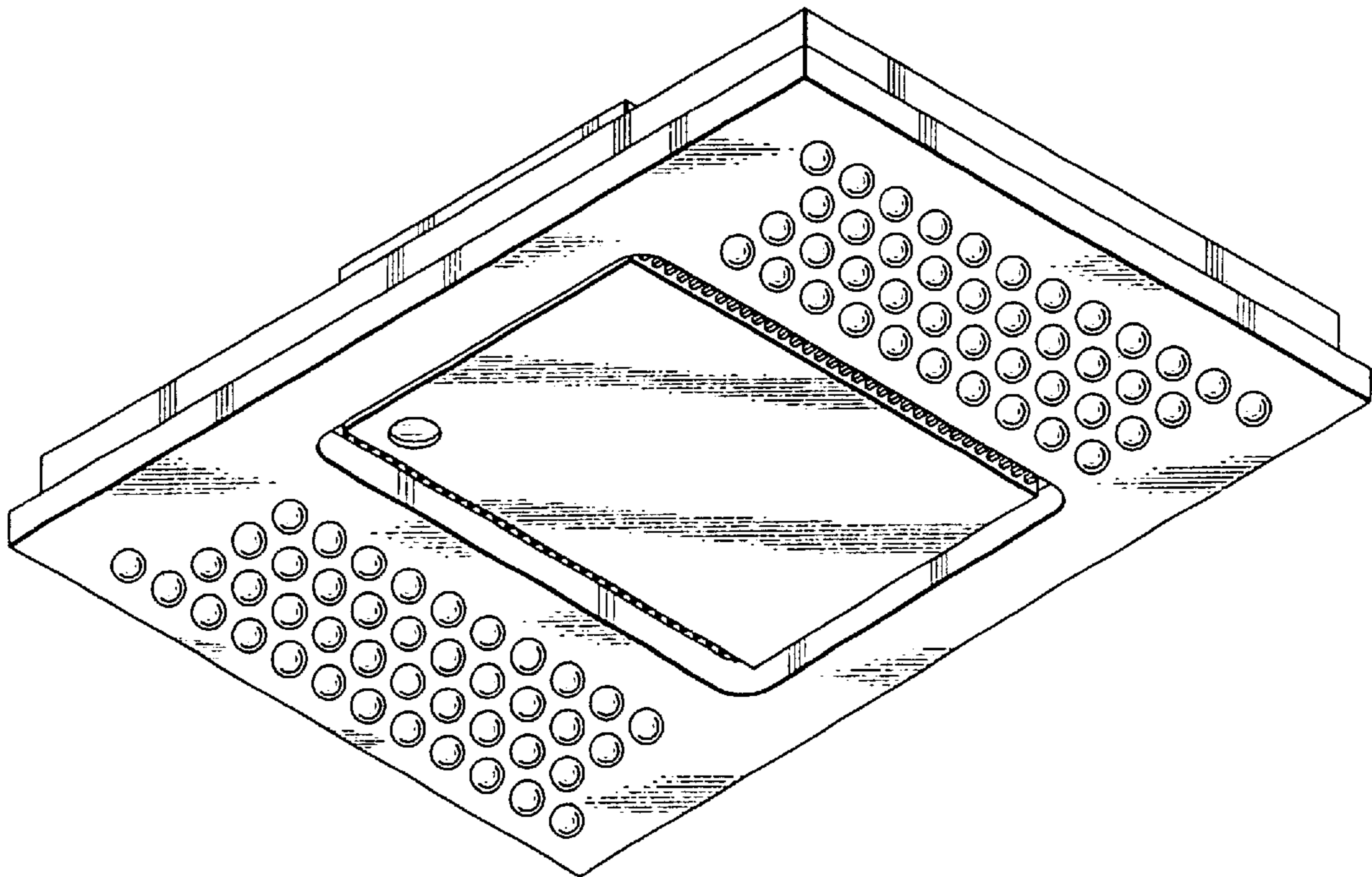


FIG.3

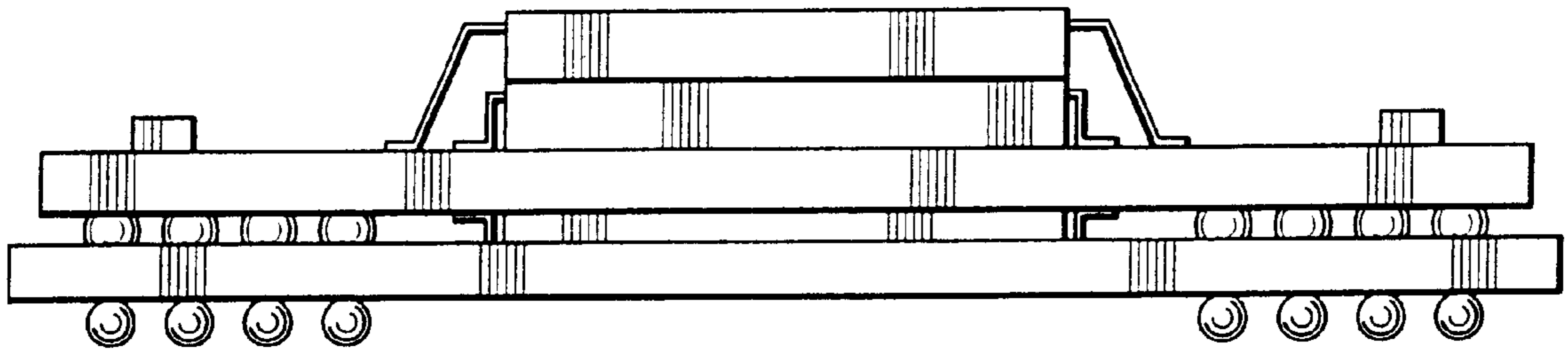


FIG.4

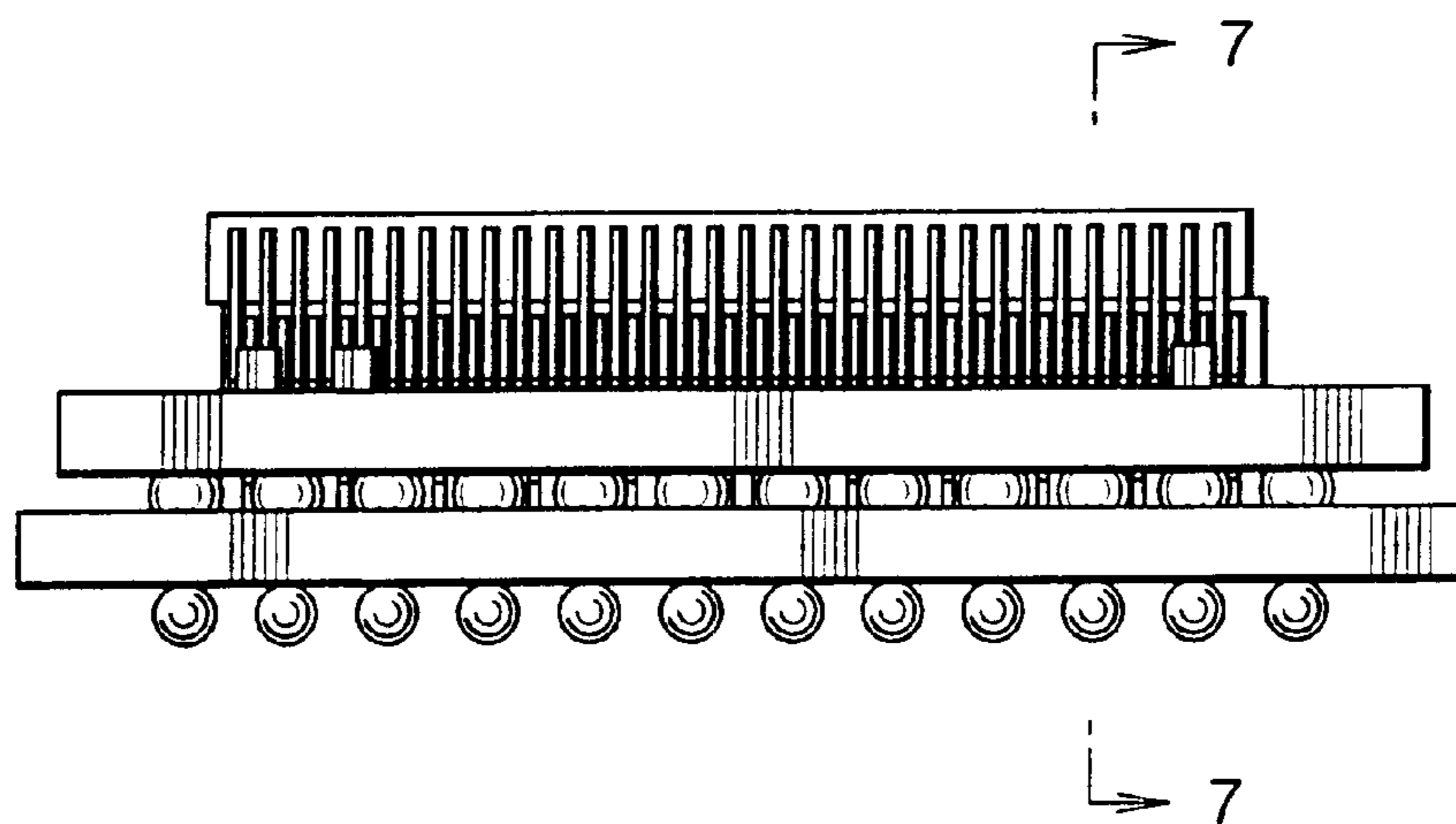


FIG. 5

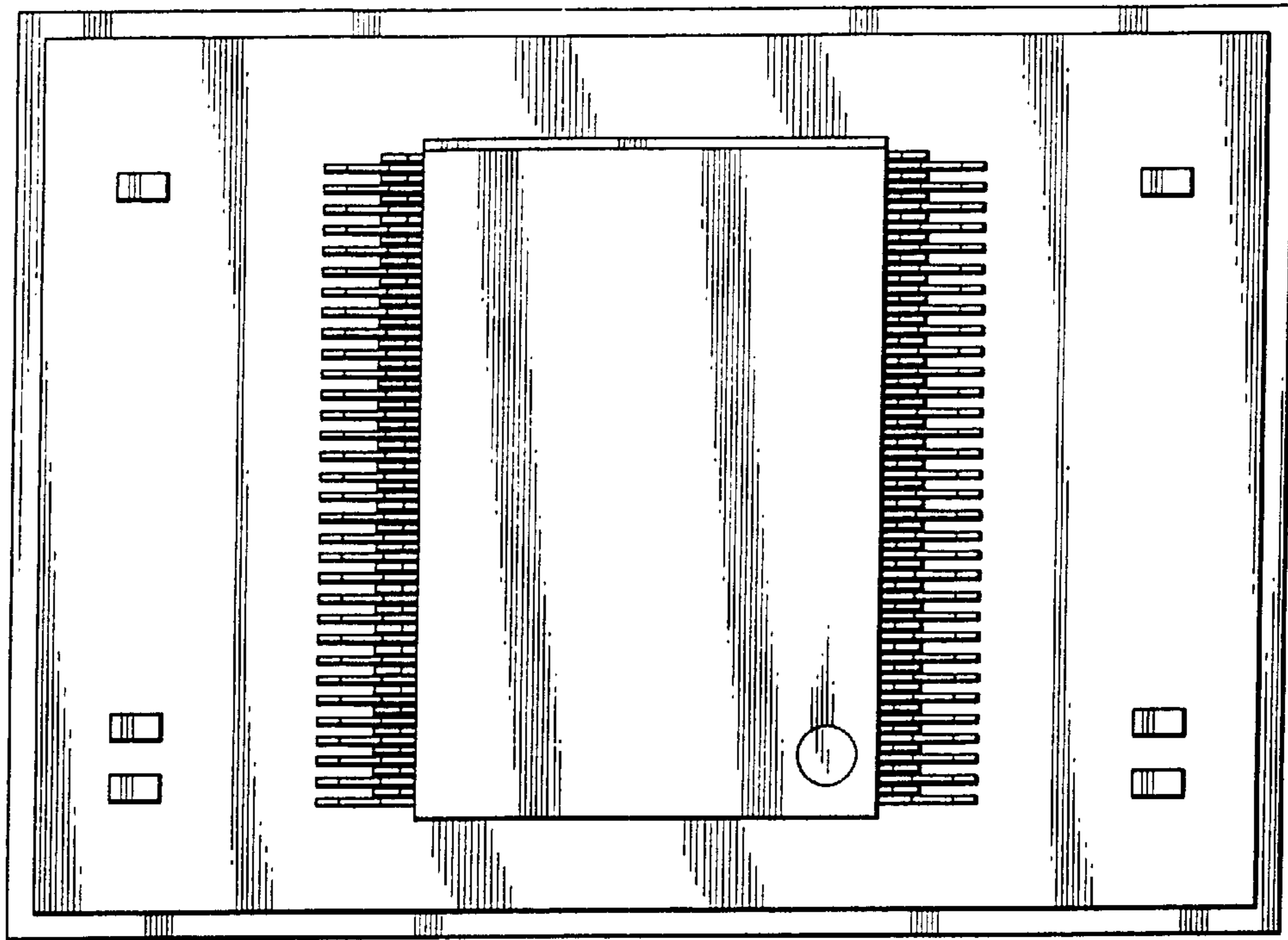


FIG. 6

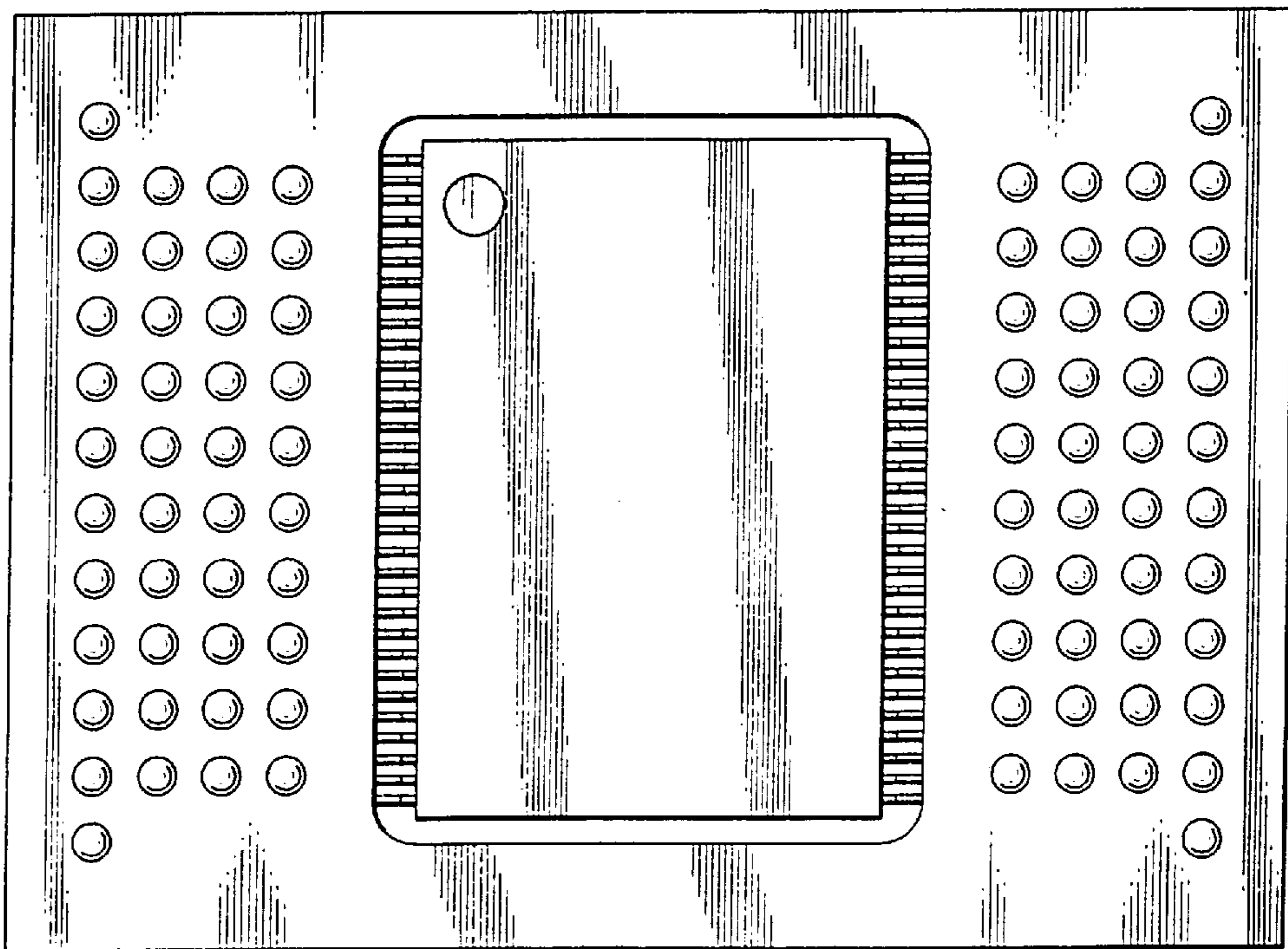


FIG. 7

